






















# Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0.50mil	3.5
4		Layer 1	Copper	1.37mil	
5		Dielectric 1	1080HR RC68	2.90mil	4.2
6		Layer 2P (G)	Copper	1.37mil	
7		Dielectric 2		5.00mil	4.2
8		Layer 3	Copper	1.37mil	
9		Dielectric 3		10.00mil	4.2
10		Layer 4P (P)	Copper	1.37mil	
11		Dielectric 4	7628HR RC46	16.00mil	4.2
12		Layer 5P (P)	Copper	1.37mil	
13		Dielectric 5		10.00mil	4.2
14		Layer 6	Copper	1.37mil	
15		Dielectric 6		5.00mil	4.2
16		Layer 7P (G)	Copper	1.37mil	
17		Dielectric 7	1080HR RC68	2.90mil	4.2
18		Layer 8	Copper	1.37mil	
19		Bottom Solder	Solder Resist	0.50mil	3.5
20		Bottom Overlay			
21		Bottom Paste			

Height : 63.76mil